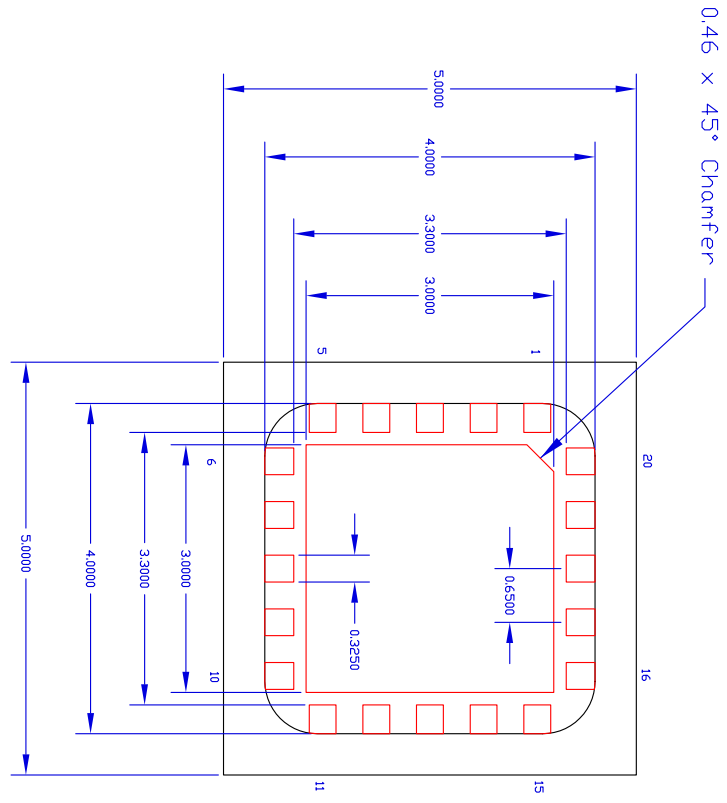
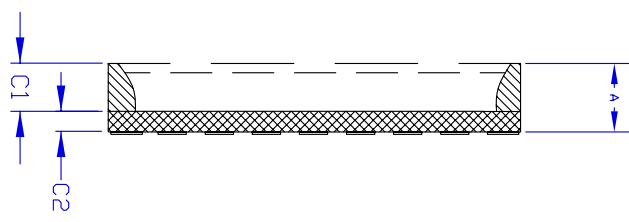


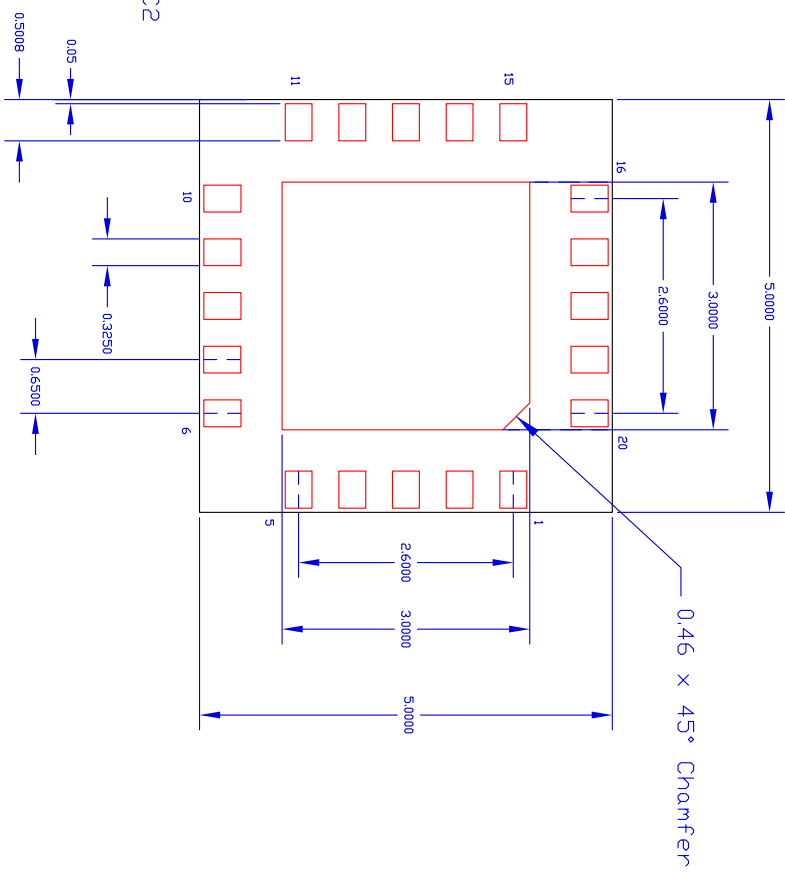
TOP VIEW



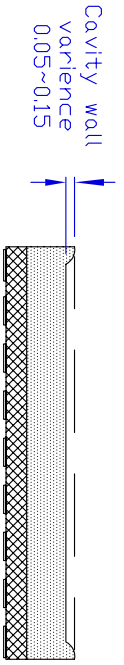
SIDE VIEW



BOTTOM VIEW



SIDE VIEW



HEIGHT TABLE

SERIES	C1	C2	A
A-QFN	0.63	0.27	0.90
A-TQFN	0.38	0.27	0.65
TOL	+/- 0.10	+/- 0.05	+/- 0.15

OTHER SIZES AVAILABLE

Note:

- Organic substrate
- Cavity Dam: Hysol FP4451TD
- Pads: Cu/Ni/Au
- Copper Thickness: 12µm~18µm (0.5~0.7mil)
- Bonding Pad Gold Thickness: 1.3µm (50 micro-inch)
- PCB Pads Gold Thickness: 0.13µm (5 micro-inch)
- Nickel Thickness: 38µm (150 micro-inch)
- All Dimensions Are mm

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TOLERANCES UNLESS NOTED:		APPROVALS		DATE	
X.XX	±	DRAWN		11/29/08	
X.XXX	±	ENG		TA	
X.XXXX	±	MFG			
ALL DIMENSIONS ARE IN:		TITLE			
□ INCHES		20-LEAD 5MM P=0.65MM			
□ MILLIMETERS		A-QFN (AIR) OPEN CAVITY			
THIRD ANGLE PROJECTION:		SCALE		SIZE	
□ INCHES		NONE		A	
□ MILLIMETERS		DRAWING NO.		462010	
REVISED		DO NOT SCALE DRAWING		SHEET 1 OF 1	

